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Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	128300
Number of Logic Elements/Cells	340000
Total RAM Bits	19456000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	780-BBGA, FCBGA
Supplier Device Package	780-HBGA (33x33)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxma3e3h29c2ln

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering (1), (2), (3) (Part 2 of 2)

Transceiver Speed				Core Spe	ed Grade			
Grade	C1	C2, C2L	C3	C4	12, 12L	13, 13L	I3YY	14
3 GX channel—8.5 Gbps	_	Yes	Yes	Yes	_	Yes	Yes ⁽⁴⁾	Yes

Notes to Table 1:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.
- (3) C2L, I2L, and I3L speed grades are for low-power devices.
- (4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering (1), (2)

Transacius Snood Crada		Core Speed Grade						
Transceiver Speed Grade	C1	C2	12	13				
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	_	_				
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes				

Notes to Table 2:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)

Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Power supply for core voltage and periphery circuitry	-0.5	1.35	V
V _{CCPT}	Power supply for programmable power technology	-0.5	1.8	V
V _{CCPGM}	Power supply for configuration pins	-0.5	3.9	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	-0.5	3.4	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	-0.5	3.9	V
V _{CCPD}	I/O pre-driver power supply	-0.5	3.9	V
V _{CCIO}	I/O power supply	-0.5	3.9	V

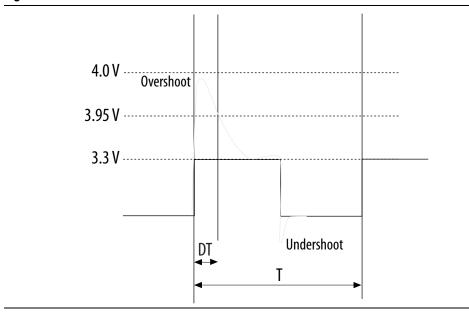
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Table 5 lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle. For example, a signal that overshoots to 3.95 V can be at 3.95 V for only ~21% over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~2 years.

Table 5. Maximum Allowed Overshoot During Transitions

Symbol	Description	Condition (V)	Overshoot Duration as % @ T _J = 100°C	Unit
		3.8	100	%
		3.85	64	%
		3.9	36	%
	AC input voltage	3.95	21	%
Vi (AC)		4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Figure 1. Stratix V Device Overshoot Duration



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Recommended Operating Conditions

This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC}	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) (3)	_	0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
V (1)	I/O pre-driver (3.0 V) power supply		2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply		2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply	_	2.85	3.0	3.15	٧
	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	_	1.71	1.8	1.89	٧
V_{CCIO}	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply		1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply		1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply		2.85	3.0	3.15	V
V_{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply		2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply		1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
V _I	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	_	0	_	V _{CCIO}	V
т.	Operating junction temperature	Commercial	0	_	85	°C
T _J	Operating junction temperature	Industrial	-40	_	100	°C

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Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
t	Dower ounds rome time	Standard POR	200 μs	_	100 ms	_
LRAMP	Fower supply rainp line	Fast POR	200 μs	_	4 ms	_

Notes to Table 6:

- (1) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.
- (2) If you do not use the design security feature in Stratix V devices, connect V_{CCBAT} to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V_{CCBAT}. Stratix V devices will not exit POR if V_{CCBAT} stays at logic low.
- (3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.
- (4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
V _{CCA_GXBL}	Transceiver channel PLL power supply (left	GX, GS, GT	2.85	3.0	3.15	V
(1), (3)	side)	७४, ७७, ७१	2.375	2.5	2.625	V
V _{CCA_GXBR}	Transceiver channel PLL power supply (right	GX, GS	2.85	3.0	3.15	V
$(1), (\overline{3})$	$(1), (\overline{3})$ side)		2.375	2.5	2.625	V
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V
	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHIP_L}	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V_{CCHIP_R}	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
V _{CCHSSI_R}	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
			0.82	0.85	0.88	
V _{CCR_GXBL}	Receiver analog power supply (left side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Treceiver arialog power supply (left side)	un, us, ui	0.97	1.0	1.03	V
			1.03	1.05	1.07	

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Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
			0.82	0.85	0.88	
V _{CCR_GXBR}	Receiver analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Treceiver analog power supply (right slue)	ux, us, u1	0.97	1.0	1.03	v
			1.03	1.05	1.07	
V _{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
			0.82	0.85	0.88	
V _{CCT_GXBL}	Transmitter analog power supply (left side)	GX, GS, GT	0.87	0.90	0.93	V
(2)			0.97	1.0	1.03	
			1.03	1.05	1.07	
			0.82	0.85	0.88	
V _{CCT_GXBR}	Transmitter analog power supply (right side)	GX, GS, GT	0.87	0.90	0.93	V
(2)	Transmitter analog power supply (right side)		0.97	1.0	1.03	V
			1.03	1.05	1.07	
V _{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V _{CCL_GTBR}	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V _{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V _{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

Notes to Table 7:

⁽¹⁾ This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.

⁽²⁾ Refer to Table 8 to select the correct power supply level for your design.

⁽³⁾ When using ATX PLLs, the supply must be 3.0 V.

⁽⁴⁾ This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

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Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices (1) (Part 2 of 2)

				Calibration Accuracy			
Symbol	Description	Conditions	C1	C2,I2	C3,I3, I3YY	C4,I4	Unit
50-Ω R _S	Internal series termination with calibration (50- Ω setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%
$34\text{-}\Omega$ and $40\text{-}\Omega$ R_S	Internal series termination with calibration (34- Ω and 40- Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%
48 - Ω , 60 - Ω , 80 - Ω , and 240 - Ω R _S	Internal series termination with calibration (48- Ω , 60- Ω , 80- Ω , and 240- Ω setting)	V _{CCIO} = 1.2 V	±15	±15	±15	±15	%
50-Ω R _T	Internal parallel termination with calibration (50-Ω setting)	V _{CCIO} = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} 20\text{-}\Omega,30\text{-}\Omega,\\ 40\text{-}\Omega,60\text{-}\Omega,\\ \text{and}\\ 120\text{-}\OmegaR_T \end{array}$	Internal parallel termination with calibration (20- Ω , 30- Ω , 40- Ω , 60- Ω , and 120- Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
60- Ω and 120- Ω R _T	Internal parallel termination with calibration (60- Ω and 120- Ω setting)	V _{CCIO} = 1.2	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} \textbf{25-}\Omega \\ \textbf{R}_{S_left_shift} \end{array}$	Internal left shift series termination with calibration (25- Ω R _{S_left_shift} setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

Note to Table 11:

Table 12 lists the Stratix V OCT without calibration resistance tolerance to PVT changes.

Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 1 of 2)

			Re	sistance	Tolerance		
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit
25-Ω R, 50-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 3.0 and 2.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 1.8 and 1.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 1.2 V	±35	±35	±50	±50	%

⁽¹⁾ OCT calibration accuracy is valid at the time of calibration only.

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Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) (1)

Symbol	Description	V _{CCIO} (V)	Typical	Unit
		3.0	0.189	
	OCT variation with temperature without recalibration	2.5	0.208	
dR/dT		1.8	0.266	%/°C
		1.5	0.273	1
		1.2	0.317	

Note to Table 13:

(1) Valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0° to $85^\circ\text{C}.$

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Description	Value	Unit
C _{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on the left and right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	pF

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
I _{IOPIN (DC)}	DC current per I/O pin	300 μΑ
I _{IOPIN (AC)}	AC current per I/O pin	8 mA ⁽¹⁾
I _{XCVR-TX (DC)}	DC current per transceiver transmitter pin	100 mA
I _{XCVR-RX (DC)}	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

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Switching Characteristics

This section provides performance characteristics of the Stratix V core and periphery blocks.

These characteristics can be designated as Preliminary or Final.

- Preliminary characteristics are created using simulation results, process data, and other known parameters. The title of these tables show the designation as "Preliminary."
- Final numbers are based on actual silicon characterization and testing. The numbers reflect the actual performance of the device under worst-case silicon process, voltage, and junction temperature conditions. There are no designations on finalized tables.

Transceiver Performance Specifications

This section describes transceiver performance specifications.

Table 23 lists the Stratix V GX and GS transceiver specifications.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 1 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trar	sceive Grade	r Speed 2	Tran	r Speed 3	Unit	
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reference Clock											
Supported I/O Standards	Dedicated reference clock pin	1.2-V	PCML,	1.4-V PCM	L, 1.5-V		2.5-V PCM HCSL	IL, Diffe	rential	LVPECL, L\	DS, and
Sidiludius	RX reference clock pin			1.4-V PCMI	_, 1.5-V	PCML,	2.5-V PCM	L, LVPE	CL, and	d LVDS	
Input Reference Clock Frequency (CMU PLL) (8)	_	40 — 710		40 — 710		40 —		710	MHz		
Input Reference Clock Frequency (ATX PLL) ⁽⁸⁾	_	100		710	100		710	100	_	710	MHz
Rise time	Measure at ±60 mV of differential signal ⁽²⁶⁾	_	_	400	_		400	_	_	400	ne
Fall time	Measure at ±60 mV of differential signal ⁽²⁶⁾	_	—	400	_	_	400	_	_	400	ps
Duty cycle	_	45	_	55	45	_	55	45	_	55	%
Spread-spectrum modulating clock frequency	PCI Express® (PCIe®)	30	_	33	30		33	30	_	33	kHz

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 2 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	Unit		
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Spread-spectrum downspread	PCle	_	0 to -0.5	_	_	0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (21)	_	_	100	_	_	100	_	_	100	_	Ω
Absolute V _{MAX} ⁽⁵⁾	Dedicated reference clock pin	_	_	1.6	_	_	1.6	_	_	1.6	V
	RX reference clock pin		_	1.2	_	_	1.2	_	_	1.2	
Absolute V _{MIN}	_	-0.4		_	-0.4		_	-0.4	_	_	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	200	_	1600	mV
V _{ICM} (AC	Dedicated reference clock pin	1050/	1000/90	00/850 ⁽²⁾	1050/	1000/90	00/850 ⁽²⁾	1050/1000/900/850 (2)			mV
coupled) ⁽³⁾	RX reference clock pin	1.	.0/0.9/0	.85 ⁽⁴⁾	1.	0/0.9/0	.85 ⁽⁴⁾	1.	V		
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	250	_	550	mV
	100 Hz	_	_	-70	_	_	-70	_	_	-70	dBc/Hz
Transmitter	1 kHz	_	_	-90	_	_	-90	_	_	-90	dBc/Hz
REFCLK Phase Noise	10 kHz		_	-100	_	_	-100	_	_	-100	dBc/Hz
(622 MHz) ⁽²⁰⁾	100 kHz	_	_	-110	_	_	-110	_	_	-110	dBc/Hz
	≥1 MHz	_	_	-120		_	-120		_	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) (17)	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	3		ps (rms)	
R _{REF} (19)	_	_	1800 ±1%	_	_	1800 ±1%	_	_	180 0 ±1%	_	Ω
Transceiver Clock	<u> </u>			_			_				
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	_	100 or 125	_	MHz

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 5 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Trai	sceive Grade	r Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	DC Gain Setting = 0		0	_	_	0		_	0	_	dB
	DC Gain Setting = 1		2	_	_	2		_	2	_	dB
Programmable DC gain	DC Gain Setting = 2		4	_	_	4	_	_	4	_	dB
	DC Gain Setting = 3	_	6	_	_	6	_	_	6	_	dB
	DC Gain Setting = 4	_	8	_	_	8	_	_	8	_	dB
Transmitter											
Supported I/O Standards	_				-	1.4-V an	ıd 1.5-V PC	ML			
Data rate (Standard PCS)	_	600	_	12200	600	_	12200	600	_	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS)	_	600	_	14100	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
	85- Ω setting		85 ± 20%	_	_	85 ± 20%	_	_	85 ± 20%	_	Ω
Differential on-	100-Ω setting		100 ± 20%	_	_	100 ± 20%	_	_	100 ± 20%	_	Ω
chip termination resistors	120-Ω setting	_	120 ± 20%	_	_	120 ± 20%	_	_	120 ± 20%	_	Ω
	150-Ω setting		150 ± 20%	_	_	150 ± 20%	_	_	150 ± 20%	_	Ω
V _{OCM} (AC coupled)	0.65-V setting	_	650	_	_	650	_	_	650	_	mV
V _{OCM} (DC coupled)	_		650	_	_	650	_	_	650	_	mV
Rise time (7)	20% to 80%	30	_	160	30	_	160	30	_	160	ps
Fall time ⁽⁷⁾	80% to 20%	30	_	160	30	_	160	30		160	ps
Intra-differential pair skew	Tx V _{CM} = 0.5 V and slew rate of 15 ps	_	_ 15 15		15	ps					
Intra-transceiver block transmitter channel-to- channel skew	eiver mitter x6 PMA bonded mode — — 120 — — 120 — — 120		ps								

Table 26 shows the approximate maximum data rate using the 10G PCS.

Table 26. Stratix V 10G PCS Approximate Maximum Data Rate (1)

Mode ⁽²⁾	Transceiver	PMA Width	64	40	40	40	32	32		
Widue (2)	Speed Grade	PCS Width	64	66/67	50	40	64/66/67	32		
	1	C1, C2, C2L, I2, I2L core speed grade	14.1	14.1	10.69	14.1	13.6	13.6		
	2	C1, C2, C2L, I2, I2L core speed grade	12.5	12.5	10.69	12.5	12.5	12.5		
	2	C3, I3, I3L core speed grade	12.5	12.5	10.69	12.5	10.88	10.88		
FIFO or Register		C1, C2, C2L, I2, I2L core speed grade								
	2	C3, I3, I3L core speed grade			8.5	Gbps				
	3	C4, I4 core speed grade								
		I3YY core speed grade	10.3125 Gbps							

Notes to Table 26:

⁽¹⁾ The maximum data rate is in Gbps.

⁽²⁾ The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 4 of 5) $^{(1)}$

Symbol/	Conditions		Transceive peed Grade			Transceive beed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps
Differential on-chip	GT channels	_	100	_	_	100	_	Ω
termination resistors	GX channels				(8)		'	
\/ (AO a a a d\)	GT channels	_	500	_	_	500	_	mV
V _{OCM} (AC coupled)	GX channels				(8)		'	
D'a a /Fall d'acc	GT channels	_	15	_	_	15	_	ps
Rise/Fall time	GX channels		<u>I</u>		(8)	I		
Intra-differential pair skew	GX channels				(8)			
Intra-transceiver block transmitter channel-to-channel skew Inter-transceiver block					(8)			
Inter-transceiver block transmitter channel-to-channel skew GX channels (8)								
CMU PLL								
Supported Data Range	_	600	_	12500	600	_	8500	Mbps
t _{pll_powerdown} (13)	_	1	_	_	1	_	_	μs
t _{pll_lock} (14)	_	_	_	10	_	_	10	μs
ATX PLL								
	VCO post- divider L=2	8000	_	12500	8000	_	8500	Mbps
	L=4	4000	_	6600	4000	_	6600	Mbps
Supported Data Rate	L=8	2000	_	3300	2000	_	3300	Mbps
Range for GX Channels	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	Mbps
Supported Data Rate Range for GT Channels	VCO post- divider L=2	9800	_	14025	9800	_	12890	Mbps
t _{pll_powerdown} (13)	_	1	_	_	1	_	-	μs
t _{pll_lock} (14)	_	_	_	10	_	_	10	μs
fPLL			•					
Supported Data Range	_	600	_	3250/ 3.125 ⁽²³⁾	600	_	3250/ 3.125 ⁽²³⁾	Mbps
t _{pll_powerdown} (13)	_	1	_	<u> </u>	1	_	_	μs

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 5 of 5) (1)

Symbol/	Conditions		Transceivei peed Grade		T Sp	Unit		
Description		Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} (14)	_	_	_	10	_	_	10	μs

Notes to Table 28:

- (1) Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the VCCR_GXB power supply level.
- (3) The device cannot tolerate prolonged operation at this absolute maximum.
- (4) The differential eye opening specification at the receiver input pins assumes that receiver equalization is disabled. If you enable receiver equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (5) Refer to Figure 5 for the GT channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (6) Refer to Figure 6 for the GT channel DC gain curves.
- (7) CFP2 optical modules require the host interface to have the receiver data pins differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (8) Specifications for this parameter are the same as for Stratix V GX and GS devices. See Table 23 for specifications.
- (9) t_{LTB} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (10) tLTD is time required for the receiver CDR to start recovering valid data after the rx is lockedtodata signal goes high.
- (11) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (12) t_{LTR_LTD_manual} is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (13) tpll powerdown is the PLL powerdown minimum pulse width.
- (14) tpll lock is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (15) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (16) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (17) For ES devices, RREF is 2000 Ω ±1%.
- (18) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (19) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (20) Refer to Figure 4.
- (21) For oversampling design to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (22) This supply follows VCCR_GXB for both GX and GT channels.
- (23) When you use fPLL as a TXPLL of the transceiver.

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Table 31. PLL Specifications for Stratix V Devices (Part 2 of 3)

Symbol	Parameter	Min	Тур	Max	Unit
→ (3) (4)	Input clock cycle-to-cycle jitter (f _{REF} ≥ 100 MHz)	_	_	0.15	UI (p-p)
t _{INCCJ} (3), (4)	Input clock cycle-to-cycle jitter (f _{REF} < 100 MHz)	-750		+750	ps (p-p)
+ (5)	Period Jitter for dedicated clock output ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	175 ⁽¹⁾	ps (p-p)
t _{OUTPJ_DC} (5)	Period Jitter for dedicated clock output (f _{OUT} < 100 MHz)	_	_	17.5 ⁽¹⁾	mUI (p-p)
+ (5)	Period Jitter for dedicated clock output in fractional PLL ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	250 ⁽¹¹⁾ , 175 ⁽¹²⁾	ps (p-p)
t _{FOUTPJ_DC} (5)	Period Jitter for dedicated clock output in fractional PLL (f _{OUT} < 100 MHz)	_	_	25 ⁽¹¹⁾ , 17.5 ⁽¹²⁾	mUI (p-p)
+ (5)	Cycle-to-Cycle Jitter for a dedicated clock output $(f_{OUT} \ge 100 \text{ MHz})$	_	_	175	ps (p-p)
t _{outccj_dc} (5)	Cycle-to-Cycle Jitter for a dedicated clock output (f _{OUT} < 100 MHz)	_	_	17.5	mUI (p-p)
+ (5)	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	250 ⁽¹¹⁾ , 175 ⁽¹²⁾	ps (p-p)
t _{FOUTCCJ_DC} ⁽⁵⁾	Cycle-to-cycle Jitter for a dedicated clock output in fractional PLL (f _{OUT} < 100 MHz)+	_	_	25 ⁽¹¹⁾ , 17.5 ⁽¹²⁾	mUI (p-p)
t _{OUTPJ_IO} (5),	Period Jitter for a clock output on a regular I/O in integer PLL ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	600	ps (p-p)
(8)	Period Jitter for a clock output on a regular I/O (f _{OUT} < 100 MHz)	_	_	60	mUI (p-p)
t _{FOUTPJ 10} (5),	Period Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	600 (10)	ps (p-p)
(8), (11)	Period Jitter for a clock output on a regular I/O in fractional PLL (f_{OUT} < 100 MHz)	_	_	60 (10)	mUI (p-p)
t _{outccj_10} (5),	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL ($f_{OUT} \ge 100$ MHz)	_	_	600	ps (p-p)
(8)	Cycle-to-cycle Jitter for a clock output on a regular I/O in integer PLL (f_{OUT} < 100 MHz)	_	_	60 (10)	mUI (p-p)
t _{FOUTCCJ_IO}	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL ($f_{OUT} \ge 100$ MHz)	_	_	600 (10)	ps (p-p)
(8), (11)	Cycle-to-cycle Jitter for a clock output on a regular I/O in fractional PLL (f_{OUT} < 100 MHz)	_	_	60	mUI (p-p)
t _{CASC_OUTPJ_DC}	Period Jitter for a dedicated clock output in cascaded PLLs ($f_{OUT} \ge 100 \text{ MHz}$)	_	_	175	ps (p-p)
(5), (6)	Period Jitter for a dedicated clock output in cascaded PLLs (f _{OUT} < 100 MHz)	_	_	17.5	mUI (p-p)
f _{DRIFT}	Frequency drift after PFDENA is disabled for a duration of 100 μs	_	_	±10	%
dK _{BIT}	Bit number of Delta Sigma Modulator (DSM)	8	24	32	Bits
k _{VALUE}	Numerator of Fraction	128	8388608	2147483648	_

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Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 3 of 4)

			C1		C2,	C2L, I	2, I2L	C3, I3, I3L, I3YY			C4,14			
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
t _{DUTY}	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	45	50	55	%
	True Differential I/O Standards	_	_	160	_	_	160	_	_	200	_	_	200	ps
t _{RISE} & t _{FALL}	Emulated Differential I/O Standards with three external output resistor networks	_		250	_	_	250	_		250	_		300	ps
	True Differential I/O Standards	_	_	150	_		150		_	150		_	150	ps
TCCS	Emulated Differential I/O Standards	_	_	300	_	_	300	_		300	_		300	ps
Receiver														
	SERDES factor J = 3 to 10 (11), (12), (13), (14), (15), (16)	150	_	1434	150	_	1434	150	_	1250	150	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4 LVDS RX with DPA (12), (14), (15), (16)	150	_	1600	150	_	1600	150	_	1600	150	_	1250	Mbps
- f _{HSDRDPA} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)	_	(7)	Mbps

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 4 of 4)

Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	I3, I3I	., I3YY		C4,I	4	Unit
Symbol	Conuntions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Ullit
	SERDES factor J = 3 to 10	(6)	_	(8)	(6)		(8)	(6)		(8)	(6)	_	(8)	Mbps
f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)		(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
DPA Mode														
DPA run length	_		_	1000 0			1000 0	_		1000 0	_	_	1000 0	UI
Soft CDR mode	•													
Soft-CDR PPM tolerance	_	_	_	300	_	_	300	_	_	300	_	_	300	± PPM
Non DPA Mode	,													
Sampling Window	_	_	_	300	_		300	_		300	_	_	300	ps

Notes to Table 36:

- (1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.
- (2) When J = 1 or 2, bypass the SERDES block.
- (3) This only applies to DPA and soft-CDR modes.
- (4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.
- (5) This is achieved by using the **LVDS** clock network.
- (6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.
- (8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.
- (9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
- (10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
- (11) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.
- (12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.
- (13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.
- (14) Requires package skew compensation with PCB trace length.
- (15) Do not mix single-ended I/O buffer within LVDS I/O bank.
- (16) Chip-to-chip communication only with a maximum load of 5 pF.
- (17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (Part 2 of 2) (2), (3)

Clock Network	Parameter	Symbol	C	1	C2, C2L	, I2 , I2L	C3, I3	3, I3L, YY	C4	,14	Unit
NEIWUIK			Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	$t_{\text{JIT(per)}}$	-25	25	-25	25	-30	30	-35	35	ps
PHY Clock	Cycle-to-cycle period jitter	t _{JIT(cc)}	-50	50	-50	50	-60	60	-70	70	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-37.5	37.5	-37.5	37.5	-45	45	-56	56	ps

Notes to Table 42:

- (1) The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.
- (2) The clock jitter specification applies to the memory output clock pins clocked by an integer PLL.
- (3) The memory output clock jitter is applicable when an input jitter of 30 ps peak-to-peak is applied with bit error rate (BER) -12, equivalent to 14 sigma.

OCT Calibration Block Specifications

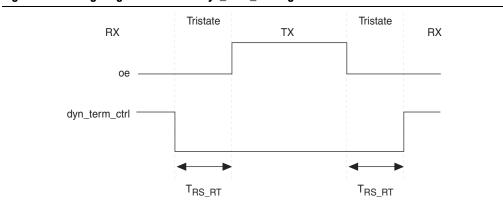
Table 43 lists the OCT calibration block specifications for Stratix V devices.

Table 43. OCT Calibration Block Specifications for Stratix V Devices

Symbol	Description	Min	Тур	Max	Unit
OCTUSRCLK	Clock required by the OCT calibration blocks	_	_	20	MHz
T _{OCTCAL}	Number of OCTUSRCLK clock cycles required for OCT $\ensuremath{R}_{\ensuremath{S}}/\ensuremath{R}_{\ensuremath{T}}$ calibration		1000	_	Cycles
T _{OCTSHIFT}	Number of OCTUSRCLK clock cycles required for the OCT code to shift out		32	_	Cycles
T _{RS_RT}	Time required between the $\mathtt{dyn_term_ctrl}$ and oe signal transitions in a bidirectional I/O buffer to dynamically switch between OCT R_S and R_T (Figure 10)	_	2.5	_	ns

Figure 10 shows the timing diagram for the oe and dyn term ctrl signals.

Figure 10. Timing Diagram for oe and dyn_term_ctrl Signals

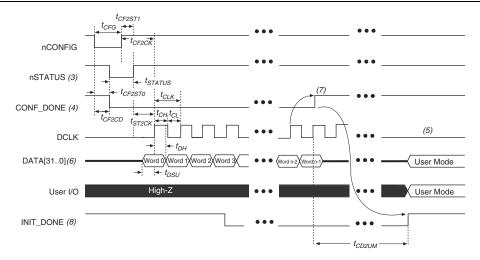


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FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is 1.

Figure 12. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1 (1), (2)



Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA[] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP ×16, use DATA [15..0]. For FPP ×8, use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the <code>INIT_DONE</code> pin is configured into the device, the <code>INIT_DONE</code> goes low.

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Table 54 lists the PS configuration timing parameters for Stratix V devices.

Table 54. PS Timing Parameters for Stratix V Devices

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	_	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low	_	600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μS
t _{STATUS}	nstatus low pulse width	268	1,506 ⁽¹⁾	μS
t _{CF2ST1}	nCONFIG high to nSTATUS high	_	1,506 ⁽²⁾	μS
t _{CF2CK} (5)	nCONFIG high to first rising edge on DCLK	1,506	_	μS
t _{ST2CK} (5)	nstatus high to first rising edge of DCLK	2	_	μS
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	0	_	ns
t _{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f _{MAX}	DCLK frequency	_	125	MHz
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μ\$
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$t_{\text{CD2CU}} + (8576 \times \text{CLKUSR} \text{ period})^{(4)}$	_	_

Notes to Table 54:

- (1) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (2) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
- (3) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section.
- (5) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Initialization

Table 55 lists the initialization clock source option, the applicable configuration schemes, and the maximum frequency.

Table 55. Initialization Clock Source Option and the Maximum Frequency

Initialization Clock Source	Configuration Schemes	Maximum Frequency	Minimum Number of Clock Cycles ⁽¹⁾
Internal Oscillator	AS, PS, FPP	12.5 MHz	
CLKUSR	AS, PS, FPP (2)	125 MHz	8576
DCLK	PS, FPP	125 MHz	

Notes to Table 55:

- $(1) \quad \text{The minimum number of clock cycles required for device initialization}.$
- (2) To enable CLKUSR as the initialization clock source, turn on the Enable user-supplied start-up clock (CLKUSR) option in the Quartus II software from the General panel of the Device and Pin Options dialog box.

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Table 60. Glossary (Part 3 of 4)

Letter	Subject	Definitions				
	SW (sampling window)	Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown: Bit Time 0.5 x TCCS RSKM Sampling Window (SW) 0.5 x TCCS				
S	Single-ended voltage referenced I/O standard	The JEDEC standard for SSTL and HSTL I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state. The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing: Single-Ended Voltage Referenced I/O Standard Voh Vih(DC) Voh Vih(DC) Voh Vih(DC) Voh Vik(AC) Voh Vik(AC)				
t _C High-speed receiver and transmitter input and output clock pe		High-speed receiver and transmitter input and output clock period.				
T	TCCS (channel- to-channel-skew)	The timing difference between the fastest and slowest output edges, including $t_{\rm CO}$ variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under SW in this table).				
		High-speed I/O block—Duty cycle on the high-speed transmitter output clock.				
	t _{DUTY}	Timing Unit Interval (TUI) The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = $1/(\text{receiver input clock frequency multiplication factor}) = t_{\text{C}}/w$)				
	t _{FALL}	Signal high-to-low transition time (80-20%) Cycle-to-cycle jitter tolerance on the PLL clock input. Period jitter on the general purpose I/O driven by a PLL.				
	t _{INCCJ}					
	t _{OUTPJ_IO}					
	t _{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL.				
	t _{RISE}	Signal low-to-high transition time (20-80%)				
U	_	_				